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ABSTRACT

LIGHT EMITTING DIODE, OPTICAL SEMICONDUCTOR DEVICE, EPOXY
RESIN COMPOSITION SUITED FOR OPTICAL SEMICONDUCTOR DEVICE,
5 AND METHOD OF MANUFACTURING THE SAME

A light emitting diode is disclosed comprising an LED chip
having a light emitting layer made of a nitride compound
semiconductor and a light transmitting resin that includes
10 a fluorescent material which absorbs at least a part of
light emitted by said LED chip and emits light of a
different wavelength, wherein said fluorescent material
includes fluorescent particles of small particle size and
fluorescent particles of large particle size, said
15 fluorescent particles of large particle size being
distributed in the vicinity of said LED chip in said light
transmitting resin to form a wavelength converting layer,
said fluorescent particles of small particle size being
distributed on the outside of said wavelength converting
20 layer in the light transmitting resin.

Fig. 1